

SMTA Press Release

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Wafer-Level Packaging Symposium Program Announced

Minneapolis, MN – The SMTA is excited to announce the technical program for the Wafer-Level Packaging Symposium. The symposium will be held February 13-15, 2024 at The Hyatt Regency San Francisco Airport in San Francisco, California.

The technical program includes over 25 expert speakers who delve into wafer-level packaging advances, 3D wafer-level integration, advanced packaging inspection, materials innovation, fan-out wafer-level packaging and manufacturing excellence. The program features presentations from leading companies including Intel Corporation, KLA Corporation, Department of Defense, and more. View the full technical program [here](#).

Additionally, the technical program features two keynote presentations. On Tuesday, February 13, 2024, Manish Dubey, Ph.D., AMD, will present, "Advanced Packaging: Key Enabler for AI." On Wednesday, February 14, 2024, Benjamin S. Cook, Meta, will present, "Wafer-Level Fan Out Technology Options to Realize High-Performance AI Enabled Augmented Reality (AR) Wearable Devices." For more information, [click here](#).

The symposium will culminate with two professional development courses on Thursday, February 15, 2024. The first course, "Polymers for Wafer-Level Packaging," will be instructed by Jeff Gotro, Ph.D., InnoCentrix, LLC, from 8:30 am – 12:00 pm (PST). Tom Dory, Ph.D., Fujifilm Electronic Materials, will instruct the second course, "Package Assembly Processes and Technology," from 1:00 pm – 4:30 pm (PST). Access to the courses is included in standard registration. For more information, click [here](#).

Registration for this event is open. Click [here](#) to register. Discounted rates are available by registering on or before January 12, 2024. All presentations, professional development courses and events open to attendees are included in registration.

For more information about the Wafer-Level Packaging Symposium, please contact Karlie Severinson at karlie@smta.org or +1-952-920-7682.

SMTA – A Global Association Working at a Local Level

The SMTA membership is an international network of professionals who build skills, share practical experience and develop solutions in electronic assembly technologies, including microsystems, emerging technologies, and related business operations.

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